

### **REMARKS/ARGUMENTS**

Claims 1, 7, 17-19, 23-25, and 31 have been amended, and claims 71 and 72 have been newly added. In addition claims 29 and 30 have been canceled. Claims 1, 3, 7-12, 14-26, 31-33, and 68-72 are now pending in the application. (Claims 2, 4-6, 13, 27, 28, and 34-67 were previously canceled.) Applicants respectfully request reexamination and reconsideration of the application in light of these amendments and remarks.

Claims 1, 3, 7-12, 14-26, 29-33, and 68-70 were rejected in view of US Patent No. 5,949,242 to Wood et al. ("Wood"), US Patent No. 6,078,845 to Friedman ("Friedman"), US Patent No. 5,528,825 to Miyauchi et al. ("Miyauchi"), and/or US Patent No. 6,184,699 to Smith ("Smith") and US Patent No. 6,264,533 to Kummeth et al. ("Kummeth"). Applicants respectfully traverse these rejections.

Independent claim 1 is directed to a method of testing singulated semiconductor dice in which the dice are deposited into a carrier that includes a digital storage device. The carrier is mounted to a substrate by placing standoffs on the carrier into sloped positioning holes on the substrate. The prior art of record (Wood, Friedman, Miyauchi, Smith, and Kummeth), whether taken individually or in combination, does not teach or suggest a carrier with standoffs that are placed in sloped positioning holes on a substrate. Therefore, claim 1 is patentable over the prior art of record. All of the other claims pending in the application depend from claim 1 and are therefore also patentable.

One advantage of the standoffs and sloped positioning holes is that the sloped positioning holes may be arranged to cause contact elements on the dice to wipe contact elements on the substrate as the standoffs are placed into the sloped positioning holes. Such a wiping action may cause the contact elements on the dice to break through oxide or other contaminants on the contact elements of the substrate, improving the electrical connections between the contact elements on the dice and the contact elements on the substrate. (The wiping action is recited in new dependent claim 72.).

Applicants note that standoffs and positioning holes are recited in issued claims in US Patent Nos. 6,627,483 and 6,644,982, which issued from applications that are related to the instant application.

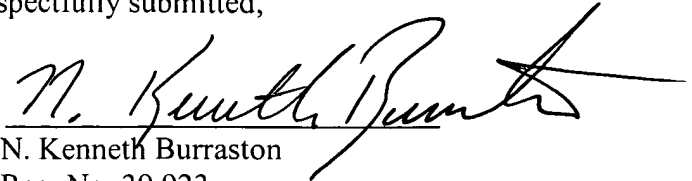
In view of the foregoing, Applicants submit that all pending claims are allowable and the application is in condition for allowance. If the Examiner believes that a discussion with

Applicants' attorney would be helpful, the Examiner is invited to contact the undersigned at  
(801) 536-6763.

Respectfully submitted,

Date: January 5, 2003

By

  
N. Kenneth Burraston  
Reg. No. 39,923

Parsons, Behle & Latimer PLC  
P.O. Box 45898  
201 South Main St., Suite 1800  
Salt Lake City, Utah 84145-0898  
Phone: (801) 536-6763  
Fax: (801) 536-6111